

ABSTRACT OF THE DISCLOSURE

A folded interposer used to achieve a high density semiconductor package is disclosed. The folded interposer is comprised of a thin, flexible material that can be folded around one or multiple semiconductor die in a serpentine fashion. The semiconductor die are then attached to a substrate through electrical contacts on the interposer. The folded interposer allows multiple semiconductor die to be efficiently stacked in a high density semiconductor package by reducing the unused or wasted space between stacked semiconductor die. Vias extending through the folded interposer provide electrical communication between the semiconductor die and the substrate. The present invention also relates to a method of packaging semiconductor die in a high density arrangement and a method of forming the high density semiconductor package.

N:\2269\4360\patapp.wpd 3/20/01